



Printed Circuit Boards
Interconnection Carriers

State of the Art: PCB's

Revisio

Datum:

Seite:

PRINTED CIRCUIT BOARDS

01

4.11.2001

1/1

Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
---	---	---	---	---	---	-----------

04 071 FR4 35 L10.70 P10

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_071_FR4_35_L10.70_p10

Layers	in μ	Material	Build-Up	Assembly
Layer-1	35 μ	Copper		
	100 μ	Prepreg		
	100 μ	Prepreg		
Layer-2	70 μ	Copper		
	100 μ	L-FR4		
Layer-3	70 μ	Copper		
	100 μ	Prepreg		
	100 μ	Prepreg		
Layer-99	35 μ	Copper		

© Copyright by Printed Circuit Boards GmbH